

REMARKS

Applicants file an RCE concurrently herewith and request further consideration of this application.

By this Amendment, Claims 1, 6 and 9 are formally amended to include the amendments previously proposed in the Request for Reconsideration dated May 12, 2004. In support of these amendments and in response to the pending rejections asserted in the Office Action dated February 2, 2004, Applicants reiterate the comments made in the Request for Reconsideration and the Examiner Interview kindly afforded to the undersigned by the Examiner.

Generally, Applicants continue to note that Bennin only discloses a laminate having the conductive material layer 70 of Bennin already present in the initial laminate. As such, the only way the existing conductive layer can be formed into a wiring circuit in Bennin is by material removal. Hence, no matter how well known the semi-additive method of Horiuchi might be, this method only adds material to a surface and is not used to remove material from an existing material layer. Thus, the semi-additive method would not be used to form the conductive traces of Bennin since this would completely change the method specifically disclosed and claimed as the invention in Bennin.

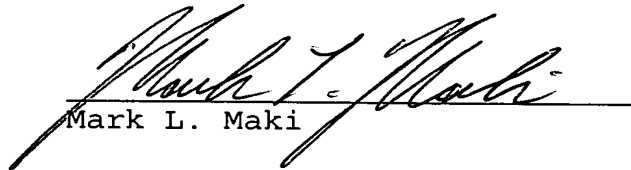
As to the plating step disclosed in Bennin, this plating is only applied to the conductive traces after their shaping by material removal and as such the plating step and etching of step of Bennin are distinctly different. Please note that Claims 12-14 of the present application claim a plating step as a fourth step which therefore distinguishes the plating step from the semi-additive step which is claimed in independent Claims 1, 6 and 9 from which Claims 12-14 respectively depend.

New Claims 15-17 are independent claims which respectively correspond to Claims 1, 6 and 9 but use alternative language to define the invention. In particular, these claims define that one of the side faces of the initial

laminate is defined by an exposed surface of the insulating layer and the wiring part is added to the exposed insulating surface to thereby cover a portion of this surface. This is believed to be distinctly different from the material removal step and the plating step of Bennin. While Horiuchi is recognized as a secondary reference, this reference does not teach material removal and its teachings therefore would not be applied to the teachings of Bennin. All of Claims 1-17 are believed allowable.

If necessary, Applicants request further discussion of the claims by telephone to address any unresolved issues or rejections.

Respectfully submitted,


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Encl: None

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